



IMAPS-UK News Release March 2010

IMAPS-UK “Beyond Solder” Technical Seminar Announced

IMAPS-UK, the UK Microelectronics Packaging Society has announced details of their one day technical seminar “Beyond Solder” being held at the National Physics Laboratory, London on the 30 June 2010, in conjunction with the Innovative electronics Manufacturing Research Centre (IeMRC).

As engineers are presented with the challenge of fitting more functionality into smaller spaces, getting more power out of devices, dissipating increasing levels of heat from components and ensuring improved levels of reliability, the methods used for interconnect are often key in achieving these goals.

The IMAPS-UK “Beyond Solder” Technical Seminar investigates the different interconnection methods being used and developed today, which overcome these challenges. These include ultrasonically bonded interconnects, reliable connections for harsh environments, conductive adhesives, press-fit connections for high reliability applications, parallel welding of ultra thin wires & ribbons, innovative die attach materials, flip chip connections & nano-scale interconnects.

The Seminar will comprise eight technical presentations in four sessions, with coffee & lunch breaks in between. These will be followed by a general discussion, which will review and assess the challenges in packaging that need to be addressed for different applications. There will also be ample opportunity for networking with fellow delegates from leading companies and institutions in the UK. In addition, there is a complementary tabletop exhibition showcasing leading companies in the field.

The event is open to all, including non IMAPS-UK members; however space for the event is limited and available on a first-come, first-served basis. Further details of the Seminar can be obtained by visiting the IMAPS-UK website www.imaps.org.uk or by emailing the Societies Secretariat: secretariat@imaps.org.uk

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About IMAPS-UK: The *International Microelectronics And Packaging Society (IMAPS)* is the largest organisation dedicated to the advancement and growth of microelectronics and electronics packaging. The United Kingdom Chapter (IMAPS-UK) provides a forum for its members via seminars, conferences, newsletters, website's etc., to ensure they are kept up to date with the latest news, developments & innovations in our field.

About the Innovative electronics Manufacturing Research Centre (IeMRC): The IeMRC is the UK's internationally recognised provider of world-class electronics manufacturing research. It focuses on sustaining and growing high value manufacturing in the UK by delivering innovative and exploitable new technologies through its highly skilled people and by providing strategic value to the electronics industry.

Additional information on IMAPS-UK can also be found on our website: <http://www.imaps.org.uk>

Additional information on IeMRC can be found at: <http://www.iemrc.org>

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